Enrique A Miranda

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3,814 30 235 53 h-index g-index citations papers 275 4,422 2.9 5.37 L-index avg, IF ext. citations ext. papers

#	Paper	IF	Citations
235	Recommended Methods to Study Resistive Switching Devices. <i>Advanced Electronic Materials</i> , 2019 , 5, 1800143	6.4	297
234	. IEEE Transactions on Electron Devices, 2011 , 58, 3124-3131	2.9	167
233	Coexistence of Grain-Boundaries-Assisted Bipolar and Threshold Resistive Switching in Multilayer Hexagonal Boron Nitride. <i>Advanced Functional Materials</i> , 2017 , 27, 1604811	15.6	149
232	Model for the Resistive Switching Effect in \$ hbox{HfO}_{2}\$ MIM Structures Based on the Transmission Properties of Narrow Constrictions. <i>IEEE Electron Device Letters</i> , 2010 , 31, 609-611	4.4	142
231	Quantum-size effects in hafnium-oxide resistive switching. <i>Applied Physics Letters</i> , 2013 , 102, 183505	3.4	139
230	Resistive switching in hafnium dioxide layers: Local phenomenon at grain boundaries. <i>Applied Physics Letters</i> , 2012 , 101, 193502	3.4	132
229	Voltage and power-controlled regimes in the progressive unipolar RESET transition of HfOEbased RRAM. <i>Scientific Reports</i> , 2013 , 3, 2929	4.9	118
228	A Model for the Set Statistics of RRAM Inspired in the Percolation Model of Oxide Breakdown. <i>IEEE Electron Device Letters</i> , 2013 , 34, 999-1001	4.4	111
227	Silicon Oxide (SiO): A Promising Material for Resistance Switching?. <i>Advanced Materials</i> , 2018 , 30, e180	114.87	105
226	. IEEE Transactions on Electron Devices, 2010 , 57, 2405-2409	2.9	92
225	Electron transport through broken down ultra-thin SiO2 layers in MOS devices. <i>Microelectronics Reliability</i> , 2004 , 44, 1-23	1.2	89
224	Soft breakdown conduction in ultrathin (3-5 nm) gate dielectrics. <i>IEEE Transactions on Electron Devices</i> , 2000 , 47, 82-89	2.9	89
223	Cycle-to-Cycle Intrinsic RESET Statistics in \${rm HfO}_{2}\$-Based Unipolar RRAM Devices. <i>IEEE Electron Device Letters</i> , 2013 , 34, 623-625	4.4	88
222	A function-fit model for the soft breakdown failure mode. <i>IEEE Electron Device Letters</i> , 1999 , 20, 265-2	674.4	58
221	Are soft breakdown and hard breakdown of ultrathin gate oxides actually different failure mechanisms?. <i>IEEE Electron Device Letters</i> , 2000 , 21, 167-169	4.4	54
220	Simulation of thermal reset transitions in resistive switching memories including quantum effects. Journal of Applied Physics, 2014 , 115, 214504	2.5	52
219	Soft breakdown fluctuation events in ultrathin SiO2 layers. <i>Applied Physics Letters</i> , 1998 , 73, 490-492	3.4	48

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218	Multi-scale quantum point contact model for filamentary conduction in resistive random access memories devices. <i>Journal of Applied Physics</i> , 2014 , 115, 244507	2.5	45
217	Impact of Intercell and Intracell Variability on Forming and Switching Parameters in RRAM Arrays. IEEE Transactions on Electron Devices, 2015, 62, 2502-2509	2.9	42
216	A simple drain current model for Schottky-barrier carbon nanotube field effect transistors. <i>Nanotechnology</i> , 2007 , 18, 025201	3.4	42
215	The Quantum Point-Contact Memristor. <i>IEEE Electron Device Letters</i> , 2012 , 33, 1474-1476	4.4	41
214	Set statistics in conductive bridge random access memory device with Cu/HfO2/Pt structure. <i>Applied Physics Letters</i> , 2014 , 105, 193501	3.4	39
213	Nonlinear conductance quantization effects in CeOx/SiO2-based resistive switching devices. <i>Applied Physics Letters</i> , 2012 , 101, 012910	3.4	39
212	({ SIM}^2{ RRAM}): a physical model for RRAM devices simulation. <i>Journal of Computational Electronics</i> , 2017 , 16, 1095-1120	1.8	37
211	Electrical characterization and modeling of pulse-based forming techniques in RRAM arrays. <i>Solid-State Electronics</i> , 2016 , 115, 17-25	1.7	37
210	Modeling the breakdown spots in silicon dioxide films as point contacts. <i>Applied Physics Letters</i> , 1999 , 75, 959-961	3.4	36
209	Standards for the Characterization of Endurance in Resistive Switching Devices. ACS Nano, 2021,	16.7	36
208	Model for multi-filamentary conduction in graphene/hexagonal-boron-nitride/graphene based resistive switching devices. <i>2D Materials</i> , 2017 , 4, 025099	5.9	33
207	On the role of Ti adlayers for resistive switching in HfO2-based metal-insulator-metal structures: Top versus bottom electrode integration. <i>Journal of Vacuum Science and Technology B:Nanotechnology and Microelectronics</i> , 2011 , 29, 01AD02	1.3	33
206	n-Monotone exact functionals. <i>Journal of Mathematical Analysis and Applications</i> , 2008 , 347, 143-156	1.1	32
205	Compact Model for the Major and Minor Hysteretic IV Loops in Nonlinear Memristive Devices. <i>IEEE Nanotechnology Magazine</i> , 2015 , 14, 787-789	2.6	29
204	A comprehensive analysis on progressive reset transitions in RRAMs. <i>Journal Physics D: Applied Physics</i> , 2014 , 47, 205102	3	28
203	Atomic layer deposited (TiO2)x(Al2O3)1½/In0.53Ga0.47As gate stacks for III-V based metal-oxide-semiconductor field-effect transistor applications. <i>Applied Physics Letters</i> , 2012 , 100, 06290	0 3 ·4	27
202	Point contact conduction at the oxide breakdown of MOS devices		24
201	Model for the voltage and temperature dependence of the soft breakdown current in ultrathin gate oxides. <i>Journal of Applied Physics</i> , 2005 , 97, 014104	2.5	24

200	Voltage-Driven Hysteresis Model for Resistive Switching: SPICE Modeling and Circuit Applications. <i>IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems</i> , 2017 , 36, 2044-2051	2.5	23
199	Resistive switching in CeO2/La0.8Sr0.2MnO3 bilayer for non-volatile memory applications. <i>Microelectronic Engineering</i> , 2015 , 147, 37-40	2.5	23
198	Detection and fitting of the soft breakdown failure mode in MOS structures. <i>Solid-State Electronics</i> , 1999 , 43, 1801-1805	1.7	21
197	Impact of the precursor chemistry and process conditions on the cell-to-cell variability in 1T-1R based HfO RRAM devices. <i>Scientific Reports</i> , 2018 , 8, 11160	4.9	20
196	Relationship among Current Fluctuations during Forming, Cell-To-Cell Variability and Reliability in RRAM Arrays 2015 ,		18
195	Volume Resistive Switching in metallic perovskite oxides driven by the Metal-Insulator Transition. Journal of Electroceramics, 2017 , 39, 185-196	1.5	18
194	Multilevel recording in Bi-deficient Pt/BFO/SRO heterostructures based on ferroelectric resistive switching targeting high-density information storage in nonvolatile memories. <i>Applied Physics Letters</i> , 2013 , 103, 263502	3.4	18
193	Failure physics of ultra-thin SiO2gate oxides near their scaling limit. <i>Semiconductor Science and Technology</i> , 2000 , 15, 445-454	1.8	18
192	Soft Breakdown in Ultrathin SiO2Layers: the Conduction Problem from a New Point of View. <i>Japanese Journal of Applied Physics</i> , 1999 , 38, 2223-2226	1.4	18
191	Effects of Ti incorporation on the interface properties and band alignment of HfTaOx thin films on sulfur passivated GaAs. <i>Applied Physics Letters</i> , 2011 , 98, 022901	3.4	17
190	Effects of high-field electrical stress on the conduction properties of ultrathin La2O3 films. <i>Applied Physics Letters</i> , 2005 , 86, 232104	3.4	17
189	Monitoring the degradation that causes the breakdown of ultrathin (. <i>IEEE Electron Device Letters</i> , 2000 , 21, 251-253	4.4	17
188	Multivariate analysis and extraction of parameters in resistive RAMs using the Quantum Point Contact model. <i>Journal of Applied Physics</i> , 2018 , 123, 014501	2.5	16
187	Resistive Switching with Self-Rectifying Tunability and Influence of the Oxide Layer Thickness in Ni/HfO2/n+-Si RRAM Devices. <i>IEEE Transactions on Electron Devices</i> , 2017 , 64, 3159-3166	2.9	16
186	Equivalent circuit modeling of the bistable conduction characteristics in electroformed thin dielectric films. <i>Microelectronics Reliability</i> , 2015 , 55, 1-14	1.2	16
185	Initial leakage current related to extrinsic breakdown in HfO2/Al2O3 nanolaminate ALD dielectrics. <i>Microelectronic Engineering</i> , 2011 , 88, 1380-1383	2.5	16
184	Statistical model for radiation-induced wear-out of ultra-thin gate oxides after exposure to heavy ion irradiation. <i>IEEE Transactions on Nuclear Science</i> , 2003 , 50, 2167-2175	1.7	16
183	Formation and Characterization of Filamentary Current Paths in \$hbox{HfO}_{2}\$-Based Resistive Switching Structures. <i>IEEE Electron Device Letters</i> , 2012 , 33, 1057-1059	4.4	15

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182	Post-radiation-induced soft breakdown conduction properties as a function of temperature. <i>Applied Physics Letters</i> , 2001 , 79, 1336-1338	3.4	15	
181	Analysis and simulation of the multiple resistive switching modes occurring in HfOx-based resistive random access memories using memdiodes. <i>Journal of Applied Physics</i> , 2019 , 125, 234503	2.5	14	
180	. IEEE Electron Device Letters, 2014 , 35, 390-392	4.4	14	
179	Investigation on the Conductive Filament Growth Dynamics in Resistive Switching Memory via a Universal Monte Carlo Simulator. <i>Scientific Reports</i> , 2017 , 7, 11204	4.9	14	
178	A physical compact DC drain current model for long-channel undoped ultra-thin body (UTB) SOI and asymmetric double-gate (DG) MOSFETs with independent gate operation. <i>Solid-State Electronics</i> , 2011 , 57, 61-66	1.7	14	
177	On the Thermal Models for Resistive Random Access Memory Circuit Simulation. <i>Nanomaterials</i> , 2021 , 11,	5.4	14	
176	(Invited) Elucidating the Origin of Resistive Switching in Ultrathin Hafnium Oxides through High Spatial Resolution Tools. <i>ECS Transactions</i> , 2014 , 64, 19-28	1	13	
175	Statistical characteristics of reset switching in Cu/HfO2/Pt resistive switching memory. <i>Nanoscale Research Letters</i> , 2014 , 9, 2500	5	13	
174	Multi-channel conduction in redox-based resistive switch modelled using quantum point contact theory. <i>Applied Physics Letters</i> , 2013 , 103, 222904	3.4	13	
173	Effects of the electrical stress on the conduction characteristics of metal gate/MgO/InP stacks. <i>Microelectronics Reliability</i> , 2009 , 49, 1052-1055	1.2	13	
172	Degradation of high-K LA2O3 gate dielectrics using progressive electrical stress. <i>Microelectronics Reliability</i> , 2005 , 45, 1365-1369	1.2	13	
171	Mesoscopic approach to the soft breakdown failure mode in ultrathin SiO2 films. <i>Applied Physics Letters</i> , 2001 , 78, 225-227	3.4	13	
170	Temperature and polarity dependence of the switching behavior of Ni/HfO2-based RRAM devices. <i>Microelectronic Engineering</i> , 2015 , 147, 75-78	2.5	12	
169	Characterization of HfO2-based devices with indication of second order memristor effects. <i>Microelectronic Engineering</i> , 2018 , 195, 101-106	2.5	12	
168	Study From Cryogenic to High Temperatures of the High- and Low-Resistance-State Currents of ReRAM NillfO2Bi Capacitors. <i>IEEE Transactions on Electron Devices</i> , 2016 , 63, 1877-1883	2.9	12	
167	DC and low-frequency noise behavior of the conductive filament in bipolar HfO2-based resistive random access memory. <i>Microelectronic Engineering</i> , 2013 , 107, 1-5	2.5	12	
166	Threshold Switching and Conductance Quantization in Al/HfO2/Si(p) Structures. <i>Japanese Journal of Applied Physics</i> , 2013 , 52, 04CD06	1.4	12	
165	BREAKDOWN MODES AND BREAKDOWN STATISTICS OF ULTRATHIN SiO2 GATE OXIDES. International Journal of High Speed Electronics and Systems, 2001 , 11, 789-848	0.5	12	

164	Study of the admittance hysteresis cycles in TiN/Ti/HfO2/W-based RRAM devices. <i>Microelectronic Engineering</i> , 2017 , 178, 30-33	2.5	11
163	A Physical Model for the Statistics of the Set Switching Time of Resistive RAM Measured With the Width-Adjusting Pulse Operation Method. <i>IEEE Electron Device Letters</i> , 2015 , 36, 1303-1306	4.4	11
162	Analytic expression for the FowlerNordheim VIIcharacteristic including the series resistance effect. <i>Solid-State Electronics</i> , 2011 , 61, 93-95	1.7	11
161	Analysis of the degradation and breakdown of thin SiO/sub 2/ films under static and dynamic tests using a two-step stress procedure. <i>IEEE Transactions on Electron Devices</i> , 2000 , 47, 2138-2145	2.9	11
160	Comparative study of the breakdown transients of thin Al2O3 and HfO2 films in MIM structures and their connection with the thermal properties of materials. <i>Journal of Applied Physics</i> , 2017 , 121, 09	47052	10
159	Switching Voltage and Time Statistics of Filamentary Conductive Paths in HfO2-Based ReRAM Devices. <i>IEEE Electron Device Letters</i> , 2018 , 39, 656-659	4.4	10
158	Coherent choice functions, desirability and indifference. Fuzzy Sets and Systems, 2018, 341, 1-36	3.7	10
157	Modeling the breakdown statistics of Al2O3/HfO2 nanolaminates grown by atomic-layer-deposition. <i>Solid-State Electronics</i> , 2012 , 71, 48-52	1.7	10
156	Modeling of hysteretic Schottky diode-like conduction in Pt/BiFeO3/SrRuO3 switches. <i>Applied Physics Letters</i> , 2014 , 105, 082904	3.4	10
155	Gate stack insulator breakdown when the interface layer thickness is scaled toward zero. <i>Applied Physics Letters</i> , 2010 , 97, 213503	3.4	10
154	A strong analogy between the dielectric breakdown of high-K gate stacks and the progressive breakdown of ultrathin oxides. <i>Journal of Applied Physics</i> , 2011 , 109, 124115	2.5	10
153	Method for extracting series resistance in MOS devices using Fowler-Nordheim plot. <i>Electronics Letters</i> , 2004 , 40, 1153	1.1	10
152	Switching events in the soft breakdown IE characteristic of ultra-thin SiO2 layers. <i>Microelectronics Reliability</i> , 1999 , 39, 161-164	1.2	10
151	Modeling of Short-Term Synaptic Plasticity Effects in ZnO Nanowire-Based Memristors Using a Potentiation-Depression Rate Balance Equation. <i>IEEE Nanotechnology Magazine</i> , 2020 , 19, 609-612	2.6	10
150	Analysis and control of the intermediate memory states of RRAM devices by means of admittance parameters. <i>Journal of Applied Physics</i> , 2018 , 124, 152101	2.5	10
149	Experimental study of the series resistance effect and its impact on the compact modeling of the conduction characteristics of HfO2-based resistive switching memories. <i>Journal of Applied Physics</i> , 2021 , 130, 054503	2.5	10
148	Study on the Connection Between the Set Transient in RRAMs and the Progressive Breakdown of Thin Oxides. <i>IEEE Transactions on Electron Devices</i> , 2019 , 66, 3349-3355	2.9	9
147	Experimental Observation of Negative Susceptance in HfO2-Based RRAM Devices. <i>IEEE Electron Device Letters</i> , 2017 , 38, 1216-1219	4.4	9

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146	Equivalent Circuit Model for the Gate Leakage Current in Broken Down \$hbox{HfO}_{2}/hbox{TaN/TiN}\$ Gate Stacks. <i>IEEE Electron Device Letters</i> , 2008 , 29, 1353-1355	4.4	9
145	Modeling of the IIV characteristics of high-field stressed MOS structures using a Fowler Nordheim-type tunneling expression. <i>Microelectronics Reliability</i> , 2002 , 42, 935-941	1.2	9
144	Lexicographic choice functions. International Journal of Approximate Reasoning, 2018, 92, 97-119	3.6	9
143	Tailoring the Switching Dynamics in Yttrium Oxide-Based RRAM Devices by Oxygen Engineering: From Digital to Multi-Level Quantization toward Analog Switching. <i>Advanced Electronic Materials</i> , 2020 , 6, 2000439	6.4	9
142	. IEEE Access, 2020 , 8, 202174-202193	3.5	9
141	Effect of the voltage ramp rate on the set and reset voltages of ReRAM devices. <i>Microelectronic Engineering</i> , 2017 , 178, 61-65	2.5	8
140	Three-state resistive switching in HfO2-based RRAM. Solid-State Electronics, 2014, 98, 38-44	1.7	8
139	An extension of the Curie-von Schweidler law for the leakage current decay in MIS structures including progressive breakdown. <i>Microelectronics Reliability</i> , 2011 , 51, 1535-1539	1.2	8
138	Degradation dynamics and breakdown of MgO gate oxides. <i>Microelectronic Engineering</i> , 2009 , 86, 1715	127.51.7	8
137	Degradation analysis and characterization of multifilamentary conduction patterns in high-field stressed atomic-layer-deposited TiO2/Al2O3 nanolaminates on GaAs. <i>Journal of Applied Physics</i> , 2012 , 112, 064113	2.5	8
136	A simple drain current model for Schottky-barrier carbon nanotube field effect transistors. <i>Nanotechnology</i> , 2007 , 18, 419001	3.4	8
135	Tunneling in sub-5 nm La2O3 films deposited by E-beam evaporation. <i>Journal of Non-Crystalline Solids</i> , 2006 , 352, 92-97	3.9	8
134	Degradation dynamics of ultrathin gate oxides subjected to electrical stress. <i>IEEE Electron Device Letters</i> , 2003 , 24, 604-606	4.4	8
133	Switching behavior of the soft breakdown conduction characteristic in ultra-thin (1998,		8
132	A common framework for soft and hard breakdown in ultrathin oxides based on the theory of point contact conduction. <i>Microelectronic Engineering</i> , 1999 , 48, 171-174	2.5	8
131	A new approach to analyze the degradation and breakdown of thin SiO2 films under static and dynamic electrical stress. <i>IEEE Electron Device Letters</i> , 1999 , 20, 317-319	4.4	8
130	Analysis on the Filament Structure Evolution in Reset Transition of Cu/HfO2/Pt RRAM Device. <i>Nanoscale Research Letters</i> , 2016 , 11, 269	5	8
129	Compact Modeling of Complementary Resistive Switching Devices Using Memdiodes. <i>IEEE Transactions on Electron Devices</i> , 2019 , 66, 2831-2836	2.9	7

128	Quantum Point Contact Conduction 2016 , 197-224		7
127	Multiple Diode-Like Conduction in Resistive Switching SiOx-Based MIM Devices. <i>IEEE</i> Nanotechnology Magazine, 2015 , 14, 15-17	2.6	7
126	Quantum point contact model of filamentary conduction in resistive switching memories 2012,		7
125	Nonhomogeneous spatial distribution of filamentary leakage current paths in circular area Pt/HfO2/Pt capacitors. <i>Journal of Vacuum Science and Technology B:Nanotechnology and Microelectronics</i> , 2013 , 31, 01A107	1.3	7
124	Electrical characterization of the soft breakdown failure mode in MgO layers. <i>Applied Physics Letters</i> , 2009 , 95, 012901	3.4	7
123	Mesoscopic approach to progressive breakdown in ultrathin SiO2 layers. <i>Applied Physics Letters</i> , 2007 , 91, 053502	3.4	7
122	Analytic model for the post-breakdown conductance of sub-5-nm SiO/sub 2/ gate oxides. <i>IEEE Electron Device Letters</i> , 2005 , 26, 673-675	4.4	7
121	Post soft breakdown conduction in SiO/sub 2/ gate oxides		7
120	Analytic modeling of leakage current through multiple breakdown paths in SiO/sub 2/ films		7
119	Memristive State Equation for Bipolar Resistive Switching Devices Based on a Dynamic Balance Model and Its Equivalent Circuit Representation. <i>IEEE Nanotechnology Magazine</i> , 2020 , 19, 837-840	2.6	7
118	Modeling of the multilevel conduction characteristics and fatigue profile of Ag/La1/3Ca2/3MnO3/Pt structures using a compact memristive approach. <i>Journal of Applied Physics</i> , 2017 , 121, 205302	2.5	6
117	Compact Modeling of the I-V Characteristics of ZnO Nanowires Including Nonlinear Series Resistance Effects. <i>IEEE Nanotechnology Magazine</i> , 2020 , 19, 297-300	2.6	6
116	Experimental Observation and Mitigation of Dielectric Screening in Hexagonal Boron Nitride Based Resistive Switching Devices. <i>Crystal Research and Technology</i> , 2018 , 53, 1800006	1.3	6
115	Modeling of the switching I-V characteristics in ultrathin (5 nm) atomic layer deposited HfO2 films using the logistic hysteron. <i>Journal of Vacuum Science and Technology B:Nanotechnology and Microelectronics</i> , 2015 , 33, 01A102	1.3	6
114	Analysis of the breakdown spots spatial distribution in large area MOS structures 2010,		6
113	An effective-field approach for the FowlerNordheim tunneling current through a metalBxideBemiconductor charged barrier. <i>Journal of Applied Physics</i> , 1997 , 82, 1262-1265	2.5	6
112	SPICE model for the current-voltage characteristic of resistive switching devices including the snapback effect. <i>Microelectronic Engineering</i> , 2019 , 215, 110998	2.5	5
111	Device variability tolerance of a RRAM-based self-organizing neuromorphic system 2018,		5

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110	Assessing the spatial correlation and conduction state of breakdown spot patterns in Pt/HfO2/Pt structures using transient infrared thermography. <i>Journal of Applied Physics</i> , 2014 , 115, 174502	2.5	5	
109	Identification of the generation/rupture mechanism of filamentary conductive paths in ReRAM devices using oxide failure analysis. <i>Microelectronics Reliability</i> , 2017 , 76-77, 178-183	1.2	5	
108	A thorough investigation of the progressive reset dynamics in HfO2-based resistive switching structures. <i>Applied Physics Letters</i> , 2015 , 107, 113507	3.4	5	
107	Analysis of the breakdown spot spatial distribution in Pt/HfO2/Pt capacitors using nearest neighbor statistics. <i>Journal of Applied Physics</i> , 2013 , 114, 154112	2.5	5	
106	Soft breakdown in MgO dielectric layers 2009 ,		5	
105	Porosity enhancement by the utilization of screening patterns in electro-perforated paper webs. <i>Journal of Electrostatics</i> , 2010 , 68, 196-199	1.7	5	
104	A drain current model for Schottky-barrier CNT-FETs. Journal of Computational Electronics, 2007, 5, 361-	-3:684	5	
103	Breakdown and anti-breakdown events in high-field stressed ultrathin gate oxides. <i>Solid-State Electronics</i> , 2001 , 45, 1327-1332	1.7	5	
102	Relation between defect generation, stress induced leakage current and soft breakdown in thin (. <i>Microelectronics Reliability</i> , 2000 , 40, 707-710	1.2	5	
101	Conduction properties of breakdown paths in ultrathin gate oxides. <i>Microelectronics Reliability</i> , 2000 , 40, 687-690	1.2	5	
100	Minimization of the Line Resistance Impact on Memdiode-Based Simulations of Multilayer Perceptron Arrays Applied to Pattern Recognition. <i>Journal of Low Power Electronics and Applications</i> , 2021 , 11, 9	1.7	5	
99	Simulation of Cycle-to-Cycle Instabilities in SiO \$_{{x}}\$ -Based ReRAM Devices Using a Self-Correlated Process With Long-Term Variation. <i>IEEE Electron Device Letters</i> , 2018 , 1-1	4.4	5	
98	Spatial analysis of failure sites in large area MIM capacitors using wavelets. <i>Microelectronic Engineering</i> , 2017 , 178, 10-16	2.5	4	
97	Exploratory study and application of the angular wavelet analysis for assessing the spatial distribution of breakdown spots in Pt/HfO2/Pt structures. <i>Journal of Applied Physics</i> , 2017 , 122, 215304	2.5	4	
96	2017,		4	
95	On the properties of conducting filament in ReRAM 2014 ,		4	
94	Failure Analysis of MIM and MIS Structures Using Point-to-Event Distance and Angular Probability Distributions. <i>IEEE Transactions on Device and Materials Reliability</i> , 2014 , 14, 1080-1090	1.6	4	
93	Soft breakdown in irradiated high-Ihanolaminates. <i>Microelectronic Engineering</i> , 2011 , 88, 1425-1427	2.5	4	

92	Mesoscopic nature of the electron transport in electroformed metal-insulator-metal switches. Journal of Vacuum Science and Technology B:Nanotechnology and Microelectronics, 2011 , 29, 01AD05	1.3	4
91	Stress Conditions to Study the Reliability Characteristics of High-k Nanolaminates. <i>ECS Transactions</i> , 2012 , 49, 161-168	1	4
90	Electron transport through electrically induced nanoconstrictions in HfSiON gate stacks. <i>Applied Physics Letters</i> , 2008 , 92, 253505	3.4	4
89	Stochastic modeling of progressive breakdown in ultrathin SiO2 films. <i>Applied Physics Letters</i> , 2003 , 83, 5014-5016	3.4	4
88	Two-step stress methodology for monitoring the gate oxide degradation in MOS devices. <i>Solid-State Electronics</i> , 2001 , 45, 1317-1325	1.7	4
87	SPICE modeling of cycle-to-cycle variability in RRAM devices. <i>Solid-State Electronics</i> , 2021 , 185, 108040	1.7	4
86	SPICE Implementation of the Dynamic Memdiode Model for Bipolar Resistive Switching Devices <i>Micromachines</i> , 2022 , 13,	3.3	4
85	Quantum conductance in memristive devices: fundamentals, developments, and applications <i>Advanced Materials</i> , 2022 , e2201248	24	4
84	Assessing the Correlation Between Location and Size of Catastrophic Breakdown Events in High-K MIM Capacitors. <i>IEEE Transactions on Device and Materials Reliability</i> , 2019 , 19, 452-460	1.6	3
83	Breakdown time statistics of successive failure events in constant voltage-stressed Al2O3/HfO2 nanolaminates. <i>Microelectronic Engineering</i> , 2015 , 147, 85-88	2.5	3
82	Model for the CurrentVoltage Characteristic of Resistive Switches Based on Recursive Hysteretic Operators. <i>IEEE Electron Device Letters</i> , 2015 , 36, 944-946	4.4	3
81	Threading dislocations in III-V semiconductors: Analysis of electrical conduction 2015,		3
80	Electrical characterization of multiple leakage current paths in HfO2/Al2O3-based nanolaminates. <i>Microelectronics Reliability</i> , 2015 , 55, 1442-1445	1.2	3
79	Modeling of the temperature effects in filamentary-type resistive switching memories using quantum point-contact theory. <i>Journal Physics D: Applied Physics</i> , 2020 , 53, 295106	3	3
78	Modeling of the Tunneling Current in MOS Devices After Proton Irradiation Using a Nonlinear Series Resistance Correction. <i>IEEE Transactions on Nuclear Science</i> , 2011 , 58, 770-775	1.7	3
77	From dielectric failure to memory function: Learning from oxide breakdown for improved understanding of resistive switching memories 2011 ,		3
76	Effects of the Semiconductor Substrate Material on the Post-breakdown Current of MgO Dielectric Layers. <i>ECS Transactions</i> , 2009 , 25, 79-86	1	3
75	Consistent model for the voltage and temperature dependence of the soft breakdown conduction mechanism in ultrathin gate oxides. <i>Microelectronic Engineering</i> , 2004 , 72, 136-139	2.5	3

74	Temperature Dependence of the Hard Breakdown Current of MOS Capacitors 2002,		3
73	BREAKDOWN MODES AND BREAKDOWN STATISTICS OF ULTRATHIN SIO2 GATE OXIDES. <i>Selected Topics in Electornics and Systems</i> , 2002 , 173-232	О	3
72	SPICE simulation of memristive circuits based on memdiodes with sigmoidal threshold functions. <i>International Journal of Circuit Theory and Applications</i> , 2018 , 46, 39-49	2	2
71	Detection of inhibitory effects in the generation of breakdown spots in HfO2-based MIM devices. <i>Microelectronic Engineering</i> , 2019 , 215, 111023	2.5	2
70	Direct observation of the generation of breakdown spots in MIM structures under constant voltage stress. <i>Microelectronics Reliability</i> , 2013 , 53, 1257-1260	1.2	2
69	From post-breakdown conduction to resistive switching effect in thin dielectric films 2012,		2
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